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T-P-9 Series – Void Filler (0.50 – 5.00mm Shore 00 65/80)

DATASHEET

T-P-9 Series (0.50-5.00mm Shore 00 65/80)

FEATURES

- Ultra-Soft with High Compressibility
- 5.0 W/mK Thermal Conductivity
- Low Thermal Impedance
- UL94 V0 Recognised
- Naturally Tacky

APPLICATIONS

- Electronic Components: IC, CPU, MOS, LED, M/B, P/S, Heat Sinks, LCD-TV's, Notebook PC, PC, Telecommunication Devices
- Wireless Hubs, DDR Modules, DVD Applications, Hand-set Applications etc.

PROPERTIES	TEST METHOD	UNIT	T-P-9 SERIES
Material	-	-	Ceramic Powder filled with Silicon Resin
Colour	Visual	-	Copper
Thickness (±10%) Increments of 0.25mm/0.01inch	ASTM-D374	mm inch	0.50 – 5.00 0.02 – 0.20
Hardness (±10)	ASTM-D2240	Shore 00	65 (≥1.0mm) 80 (<1.0mm)
Thermal Conductivity	ASTM-D5470	W/mK	5.0
Flammability Rating	UL94 V0 IEC 60695-11-10	-	UL94-V0
Dielectric Breakdown Voltage (1mm)	ASTM-D149	kV	≥6
Permittivity (1MHz)	ASTM-D150	-	6.70
Specific Gravity (±0.2)	ASTM-D792	g/cm^3	3.21
Working Temperature	EM344	˚C	-40 to 200
Volume Resistance	ASTM-D257	Ohm-cm	10^8
Tensile Strength	ASTM-D412-1998A	MPa	0.15

Note:
1. Customised shapes are available;
2. The above performance data is tested in an environment of 70% humidity, temperature 25℃.
3. This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.

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